



Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

Seite:

PRINTED CIRCUIT BOARDS

01

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 215 FR4 35 L36.70 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_215_FR4_35_L36.70_p18

Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-2	70 μ	Copper		
	360 μ	L-FR4		
Layer-3	70 μ	Copper		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-4	70 μ	Copper		
	360 μ	L-FR4		
Layer-5	70 μ	Copper		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-99	35 μ	Copper		

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